

App. No. 10/708,224
Amendment dated July 5, 2005
Reply to Office action of April 5, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the present application.

Listing of Claims:

Claim 1 (currently amended): For a semiconductor manufacturing device, a wafer holder comprising:

a substrate having a wafer-carrying side and a shaft-joining side, said shaft-joining side lent a planarity of 0.5 mm or less, and a surface roughness of 5 μ m or less in Ra; and

a substrate-supporting shaft having a substrate-joining face lent a planarity of 0.5 mm or less, and a surface roughness of 5 μ m or less in Ra, and being of a substance whose difference in thermal expansion coefficient with the substrate is 5×10^{-6} K or less, said shaft being joined to said shaft-joining side of said substrate such that a distance a between the center axis of said shaft and the axial center of said wafer-carrying side of said substrate is 5% or less of the diameter L of the wafer-carrying side, and said shaft being of a substance whose difference in thermal expansion coefficient with the substrate is 5×10^{-6} K or less, such that whereby the temperature distribution in the wafer-carrying side of said substrate is within $\pm 1.0\%$.

Claim 2 (original): A wafer holder as set forth in claim 1, being a ceramic susceptor including at least a resistive heating element.

Claim 3 (original): A semiconductor manufacturing device in which a wafer holder as set forth in claim 1 is installed.

Claim 4 (original): A semiconductor manufacturing device in which a wafer holder as set forth in claim 2 is installed.